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PATENT NUMBER and ISSUE DATE
6596569

U.S. UTILITY Patent Application

APPL. NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10063572	05/03/2002	438	108	2812	

JC3 Rc895

**APPLICANTS: Hsu Chi-Hsing;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:
TAIWAN 90132737 12/28/2001

PG PUB DO NOT PUBLISH ☐ | RESCIND ☐

Foreign priority claimed ☒ yes ☐ no
35 USC 119 conditions met ☒ yes ☐ no
Verified and Acknowledged Examiners's intials

ATTORNEY DOCKET NO
8289-US-PA

TITLE : Wafer level packaging and chip structure

U.S.DEPT. OF COMM./PAT.& TM-PTO-436L(Rev. 12-

6/19/03 Formal Drawings (7 sht/s) set 5/3/02

NOTICE OF ALLOWANCE MAILED	Assistant Examiner	CLAIMS ALLOWED	
3-12-03	Lynne A. Gurley	Total Claims: 16	Print Claim for O.G: 1
ISSUE FEE DUE		DRAWING	
Amount Due: $1600	Date Paid: 5-28-03	Sheets Drwg.: 7	Figs.Drwg.: 13
☐ TERMINAL DISCLAIMER	Lynne A. Gurley Primary Examiner	Print Fig.: 9	
	PREPARED FOR ISSUE	Application Examiner	

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